





dispence

mount

reflow

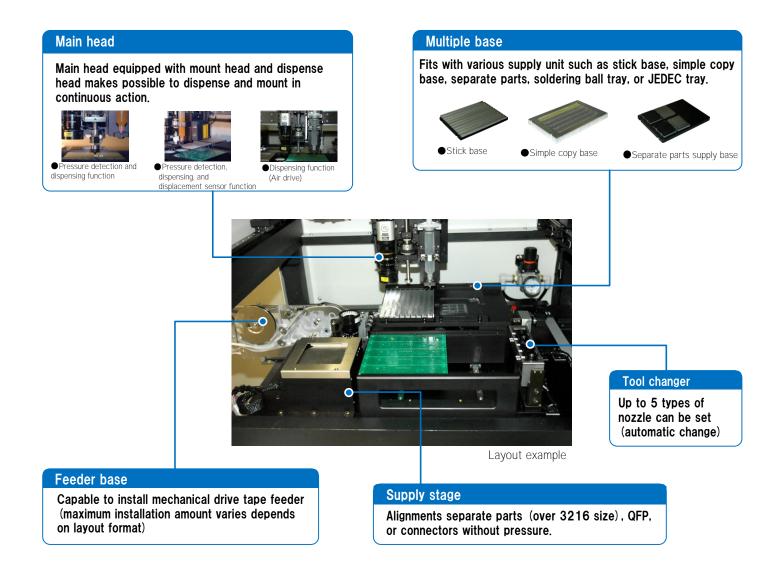
ALL in One

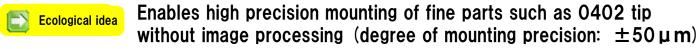


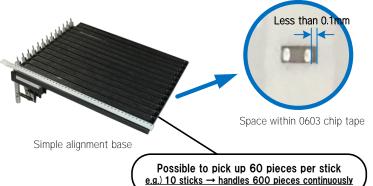
For Laboratory and Development

Ecological solution for multiple usage

Answers to your needs from mounter to die-bonder







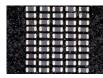
Easy alignment: Set up can be completed simply by putting tape on multi-base.

Special expertise, like image processing, is not required.

- Perfect for test mounting from 0402 to 1005 sizes
- Two-stage absorption minimizes pickup impact
- Reduces equipment cost

High precision/high rigidity casting frame

Main base made of casting frame provides stable and high precision mounting.



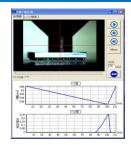


Narrow adjacent mounting of 0402 (95 μ m)

Loading control

Mounting at best loading pressure is achievable by controlling mounting axis lowering level calculated from pressure sensor measurement.

Also, by monitoring pressure status from side camera, lowering level and cream soldering movement can be put into data



Copying unit

Stable film thickness setup is possible. Corresponds to pin copy movement as well using copy nozzle.





Copy nozzle

Wafer supply

Parts can be supplied from wafer (up to 4 inches).

Suitable for test production or research.

With a combination of pin copy and adhesive pasting, the unit can be used as a die-bonder.



Removing part from UV sheet

Static photo function

Automatic photo shooting (jpg) of top surface after printing, mounting and reflow is available.

Still images are displayed in one screen simultaneously, and you can make comparative observation of each stage.



Line drawing function

Line drawing function is added in addition to paste dispensing movement. (straight or diagonal line)

This function can be used for adhesive pasting after mounting as well.



NEW

Mechanical centering function

This unit can be used with various parts type because alignment is done without pressure to the part's lead. You can start production work immediately since complicated data preparation is not necessary.



Manual mounting

All operation, from removing parts to mounting parts, can be done manually.

Also, you can easily adjust lowering level for mounting manually using side observation camera.



Dispense, mount, and reflow

Work from dispensing to mounting is executed in continuous movement. You can use this equipment for difficult work such as dispensing cream soldering on tiny board or reimplementation. Use with point reflow allows 3 steps in one device automatically. If you install bottom heater to the work

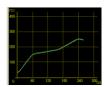
If you install bottom heater to the work base of this unit, even curing of adhesive (such as conductive adhesive) can be completed in one device. (Max heat temperature: approx. 160°C)



Point reflow

Attached arm reflow head enables to begin reflow operation without moving mount board.

You can set profiles up to 10 steps.





Profile execution example

Specifications

Item		Detail
Main unit	Size	740×700×600[mm]
	Color	Standard color
Work size	Size	30×50 ~ 200×300[mm] (varies depending on layout)
	Thickness	1. 0 ~ 3. 2[mm]
	Board positioning	Exterior hold / left foreground standard
Parts supply	Chip stick	Designed for 8mm wide cut tape / mount 20 (2 stick bases for 10)
	Waffle tray	2 to 4 inches with special palette (optional) / 150 x 200mm size at use's option
	Supply stage	□3mm~30mm size parts
Parts suction	Special bit	Special bit (prepare 5 at most)
Minimum resolution	X, Y axis	2[μm]
	Z axis	5[μm]
	Θ axis	0.036[°]
Machine accuracy	Stopping accuracy	±2 pulse
Mount accuracy	Automatic image processing	±40[µm]
Mountable parts	Parts types	Separate parts, cut tapes, waffle trays
	Shape / height	Square shape, flat bottom/4[mm]
Mount data format	New document	TXT file
	Update	CSV file
Other	Power / Power consumption	AC100[V] 50/60[Hz]
	Air pressure / consumption	0. 5~0. 7[Mpa] / 0. 2[NL/min]

*Above is subject to change accordance with functional improvement without prior notice.

--- Related product -----

Multi robot station **MRS-850**



Continuous operation of 3 processes (Dispense/Mount/Reflow) in one device!!







- Automated cell production
- Correspond to conveyer built-in spec
- Perfect for boards with few parts or small quantity such as FPC or LED boards
- Usable as point heating unit

Item	Detail
Main size	740×700×600[mm]
Work size	30X50 ~ 200X150[mm] (Layout can be accommodated at user's option)
Mount function	Mounting parts : Chip parts over 1005 size (Parts supplied from cut tape or tape feeder)
Modific full ction	Alignment method : Collet (Automatic image processing → optional)
Dispense function	Parameter : Dispense axis, duration, and holding time are user-settable
Dispense function	Syringe size : 10cc
Reflow function	Heater : Hot air + IR heater
Kenow function	Parameter : Heating time (6 to 15 seconds) / with air volume control screw



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